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U.S. Department of Commerce
Patent and Trademark Office
Attorney Docket No. 01261.0025
Attorney Customer Number: 22,852

To the Director of the U.S. Patents and

and registered original documents or copy thereof.

4-2007

1. Name of conveying party(ies):
Hee Bok KANG
Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies):
Name: **HYNIX SEMICONDUCTOR INC.**
Internal Address:

3. Nature of conveyance/Execution Date(s):
Execution Date: **April 12, 2007**
 Assignment Merger
 Security Agreement Change of Name
 Joint Research Agreement
 Government Interest Assignment
 Executive Order 9424, Confirmatory License
 Other

Street Address: **San 136-1, Ami-ri, Bubal-eup, Icheon-si, Gyeonggi-do 467-701, Korea**
City:
State: Zip Code:

Additional name(s) & Address(es) attached?
 Yes No

4. Application number(s) or patent number(s):
A. Patent Application Number(s):
Additional numbers attached?

This document is being filed together with a new application
B. Patent Number(s):
 Yes No **11/785866**

5. Name and address of to whom correspondence concerning document should be mailed:
Name: **Mr. Ernest F. Chapman**
Internal Address: **FINNEGAN, HENDERSON, FARABOW, GARRETT & DUNNER, L.L.P.**
Street Address: **901 New York Avenue, NW**
City: **Washington, D.C.**
State: Zip: **20001-4413**

6. Total number of applications and registrations involved: **1**
7. Total fee (37 CFR 3.41): **\$40**
 Authorized to be charged by credit card
 Authorized to be charged to deposit account
 Enclosed (Please charge deficiency to deposit account)
 None required (government interest not affecting title)
8. Payment Information
a. Credit Card Last 4 Numbers _____ Expiration Date _____
b. Deposit Account No.: **06-0916**
Authorized User Name _____

9. Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Ernest F. Chapman
Reg. No. 25,961

Signature
04/23/2007 YPOLITE1 00000004 11785866
06 FC:ARP1
April 20, 2007
Date

Total number of pages including cover sheet, attachments and documents: 3

Attorney Docket No.:

JOINT INVENTION
(U.S. Rights Only)

ASSIGNMENT

WHEREAS, We, the below named inventors, (hereinafter referred to as assignors, have made an invention entitled:

INTEGRATED CIRCUIT AND MANUFACTURING METHOD THEREOF

for which we executed an application for United States Letters Patent
concurrently herewith or on or filed an application for United
States Letters Patent on (Application No.);
and

WHEREAS, Hynix Semiconductor Inc., a corporation of Republic of Korea, whose post office address is San 136-1, Ami-ri, Bubal-eup, Icheon-si, Gyeonggi-do 467-701, Korea. (hereinafter referred to as assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, we, as assignors, have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, our entire right, title, and interest in and to this invention and this application; and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and we hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, WE HEREBY further covenant and agree that we will, without further consideration, communicate with assignee, its successors and assigns, any facts known to us respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, WE HEREBY authorize and request the attorneys we have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. ; filed) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, we have hereunto set our hands.

First Assignor

Assignor: Hee Bok KANG

Address: #106-801 Byeoksan Apt., 762 Gagyeong-dong, Heungdeok-gu,
Cheongju-si, Chungcheongbuk-do 361-730, Korea

Citizenship: Republic of Korea

Signature: Kang Hee Bok

Date: April 12, 2007

Second Assignor

Assignor: _____

Address: _____

Citizenship: _____

Signature: _____

Date: _____

Third Assignor

Assignor: _____

Address: _____

Citizenship: _____

Signature: _____

Date: _____